



Product Change Notification - GBNG-13FLUE758

Date:

28 Jan 2020

Product Category:

8-bit Microcontrollers; Capacitive Touch Sensors; Others

Affected CPNs:**Notification subject:**

CCB 3702 and 3702.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach and G700LTD mold compound material for selected Atmel products of the 35.4K and 35.5K wafer technologies available in 32L and 64L VQFN packages at NSEB assembly site.

Notification text:**PCN Status:**

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach and G700LTD mold compound material for selected Atmel products of the 35.4K and 35.5K wafer technologies available in 32L and 64L VQFN packages at NSEB assembly site.

Pre Change:

Using gold (Au) bond wire, 8200T die attach and G770HCD mold compound material.

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach and G700LTD mold compound material.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	UTAC Thai Limited LTD. (NSEB)	UTAC Thai Limited LTD. (NSEB)
Wire material	Au	CuPdAu
Die attach material	8200T	8600
Molding compound material	G770HCD	G700LTD
Lead frame material	EFTEC 64T	EFTEC 64T

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve on-time delivery performance by qualifying palladium coated copper with gold flash (CuPdAu) bond wire.

Change Implementation Status:

In Progress

Estimated First Ship Date:

February 29, 2020 (date code: 2009)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.



Time Table Summary:

	March 2019					->	January 2020					February 2020			
Workweek	09	10	11	12	13		01	02	03	04	05	06	07	08	09
Initial PCN Issue Date				X											
Qual Report Availability											X				
Final PCN Issue Date											X				
Estimated Implementation Date															X

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:

March 22, 2019: Issued initial notification.

January 28, 2020: Issued final notification. Attached the qualification report. Provided estimated first ship date to be on February 29, 2020.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_GBNG-13FLUE758_Qual_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

ATTINY88-15MZ
AT42QT1110-MZ
ATTINY88HGM-15MZ
ATTINY88-15MZVAO
ATTINY261-15MZ
ATTINY261ECL-15MZ
ATMEGA88PA-15MZ
ATMEGA168PA-15MZ
ATTINY861-15MZ
ATTINY461-15MZ
ATMEGA328P-15MZ
ATMEGA48PA-15MZ
ATTINY87-A15MZ
ATTINY167-A15MZ
ATMEGA88-15MT1
ATMEGA88V-15MT
ATMEGA48-15MT1
ATMEGA48-15MT
ATMEGA48-15MZ
ATMEGA168-15MZT
ATMEGA168-15MT1
ATMEGA168-15MT
ATMEGA168-15MZ
ATMEGA169P-15MT
AT90CAN64-15MT1
AT90CAN64-15MT
AT90CAN64-15MZ
AT90CAN128-15MT1
AT90CAN128-15MT
AT90CAN128-15MZ